

Full Material Declaration for attached parts list

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Diotec Semiconductor AG

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Declarations authorised by:

Udo Steinebrunner, Product Manager, -

Declaration effective from: 1 May 2009 [Approved on 24 February 2023, 14:10 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	0.5%	Nickel REACH Article 67 Exemption	7440-02-0	1%
			Gold	7440-57-5	11.5%
			Polydimethylsiloxane rubber	63394-02-5	25%
			Silicon	7440-21-3	62.5%
Die attach	Lead and Lead alloys	0.1%	Silver	7440-22-4	2.5%
			Tin	7440-31-5	5%
			Lead EU RoHS Exemption 7(a) Exempt from other regulatory requirements Exempt from other regulatory requirements	7439-92-1	92.5%
Encapsulation	EP (Epoxy resin)	61.2%	Carbon black	1333-86-4	0.3%
			ANTIMONY TRIOXIDE Exempt from other regulatory requirements	1309-64-4	0.8%
			Tetrabromobisphenol A (TBBPA) Exempt from other regulatory requirements	79-94-7	0.99%
			Epoxy resin 89	26335-32-0	27.61%
			Quartz sand	60676-86-0	70.3%
Leadfinish	Tin plating	0.16%	Copper	7440-50-8	0.7%
			Silver	7440-22-4	2.8%
			Tin	7440-31-5	96.5%

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Leadframe	Copper (e.g. copper amounts in cable harnesses)	38.04%	Nickel	7440-02-0	0.4%
			REACH Article 67 Exemption Copper	7440-50-8	99.6%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
KBPCxxxx(F)P/I	Bridge Rectifier Square	17	g